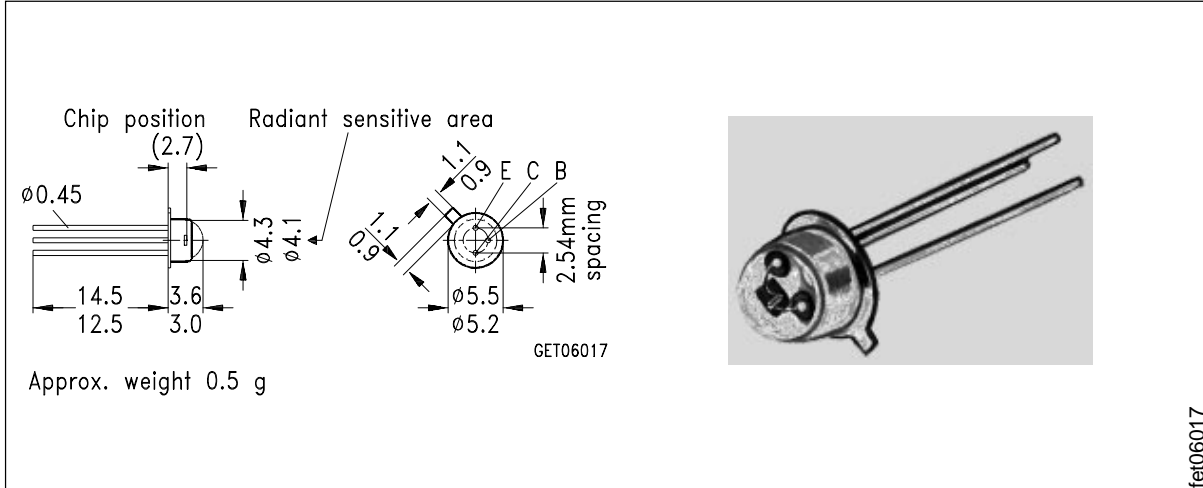


## NPN-Silizium-Fototransistor Silicon NPN Phototransistor

BP 103



Maße in mm, wenn nicht anders angegeben/Dimensions in mm, unless otherwise specified.

### Wesentliche Merkmale

- Speziell geeignet für Anwendungen im Bereich von 420 nm bis 1130 nm
- Hohe Linearität
- TO-18, Bodenplatte, klares Epoxy-Gießharz, mit Basisanschluß

### Anwendungen

- Computer-Blitzlichtgeräte
- Lichtschranken für Gleich- und Wechsellichtbetrieb
- Industrieelektronik
- "Messen/Steuern/Regeln"

### Features

- Especially suitable for applications from 420 nm to 1130 nm
- High linearity
- TO-18, base plate, transparent epoxy resin lens, with base connection

### Applications

- Computer-controlled flashes
- Photointerrupters
- Industrial electronics
- For control and drive circuits

| Typ<br>Type            | Bestellnummer<br>Ordering Code |
|------------------------|--------------------------------|
| BP 103                 | Q62702-P75                     |
| BP 103-2               | Q62702-P79-S1                  |
| BP 103-3               | Q62702-P79-S2                  |
| BP 103-4               | Q62702-P79-S4                  |
| BP 103-5 <sup>1)</sup> | Q 62702-P781                   |

1) Lieferung in dieser Gruppe kann wegen Ausbeuteschwankungen nicht immer sichergestellt werden. Wir behalten uns in diesem Fall die Lieferung einer Ersatzgruppe vor.

1) Supplies out of this group cannot always be guaranteed due to unforeseeable spread of yield. In this case we will reserve us the right of delivering a substitute group.

**Grenzwerte**  
**Maximum Ratings**

| Bezeichnung<br>Description  | Symbol<br>Symbol  | Wert<br>Value | Einheit<br>Unit |
|---|-------------------|---------------|-----------------|
| Betriebs- und Lagertemperatur<br>Operating and storage temperature range  | $T_{op}; T_{stg}$ | - 40 ... + 80 | °C              |
| Löttemperatur bei Tauchlötung<br>Lötstelle $\geq 2$ mm vom Gehäuse,<br>Lötzeit $t \leq 5$ s<br>Dip soldering temperature, $\geq 2$ mm distance<br>from case bottom $t \leq 5$ s   | $T_s$             | 260           | °C              |
| Löttemperatur bei Kolbenlötung<br>Lötstelle $\geq 2$ mm vom Gehäuse,<br>Lötzeit $t \leq 3$ s<br>Iron soldering temperature, $\geq 2$ mm distance<br>from case bottom $t \leq 3$ s | $T_s$             | 300           | °C              |
| Kollektor-Emitterspannung<br>Collector-emitter voltage  | $V_{CE}$          | 50            | V               |
| Kollektorstrom<br>Collector current   | $I_C$             | 100           | mA              |
| Kollektorspitzenstrom, $\tau < 10 \mu s$<br>Collector surge current   | $I_{CS}$          | 200           | mA              |
| Emitter-Basisspannung<br>Emitter -base voltage  | $V_{EB}$          | 7             | V               |
| Verlustleistung, $T_A = 25 \text{ °C}$<br>Total power dissipation   | $P_{tot}$         | 150           | mW              |
| Wärmewiderstand<br>Thermal resistance   | $R_{thJA}$        | 500           | K/W             |

**Kennwerte** ( $T_A = 25\text{ °C}$ ,  $\lambda = 950\text{ nm}$ )

**Characteristics**

| Bezeichnung<br>Description   | Symbol<br>Symbol                                      | Wert<br>Value    | Einheit<br>Unit |
|--|---|------------------|-----------------|
| Wellenlänge der max. Fotoempfindlichkeit<br>Wavelength of max. sensitivity   | $\lambda_{S\text{ max}}$                              | 850              | nm              |
| Spektraler Bereich der Fotoempfindlichkeit<br>$S = 10\%$ von $S_{\text{max}}$<br>Spectral range of sensitivity<br>$S = 10\%$ of $S_{\text{max}}$   | $\lambda$   | 420 ... 1130     | nm              |
| Bestrahlungsempfindliche Fläche<br>Radiant sensitive area  | $A$   | 0.12             | mm <sup>2</sup> |
| Abmessungen der Chipfläche<br>Dimensions of chip area  | $L \times B$<br>$L \times W$                          | 0.5 × 0.5        | mm × mm         |
| Abstand Chipoberfläche zu Gehäuseoberfläche<br>Distance chip front to case surface   | $H$   | 0.2 ... 0.8      | mm              |
| Halbwinkel<br>Half angle   | $\varphi$   | ± 55             | Grad<br>deg.    |
| Fotostrom der Kollektor-Basis-Fotodiode<br>Photocurrent of collector-base photodiode<br>$E_e = 0.5\text{ mW/cm}^2$ , $V_{\text{CB}} = 5\text{ V}$<br>$E_v = 1000\text{ lx}$ , Normlicht/standard light a<br>$V_{\text{CB}} = 5\text{ V}$ | $I_{\text{PCB}}$<br>$I_{\text{PCB}}$                  | 0.9<br>2.7       | µA<br>µA        |
| Kapazität<br>Capacitance<br>$V_{\text{CE}} = 0\text{ V}$ , $f = 1\text{ MHz}$ , $E = 0$<br>$V_{\text{CB}} = 0\text{ V}$ , $f = 1\text{ MHz}$ , $E = 0$<br>$V_{\text{EB}} = 0\text{ V}$ , $f = 1\text{ MHz}$ , $E = 0$                    | $C_{\text{CE}}$<br>$C_{\text{CB}}$<br>$C_{\text{EB}}$ | 8<br>11<br>19    | pF<br>pF<br>pF  |
| Dunkelstrom<br>Dark current<br>$V_{\text{CE}} = 35\text{ V}$ , $E = 0$   | $I_{\text{CEO}}$                                      | 5 ( $\leq 100$ ) | nA              |

Die Fototransistoren werden nach ihrer Fotoempfindlichkeit gruppiert und mit arabischen Ziffern gekennzeichnet.

The phototransistors are grouped according to their spectral sensitivity and distinguished by arabian figures.

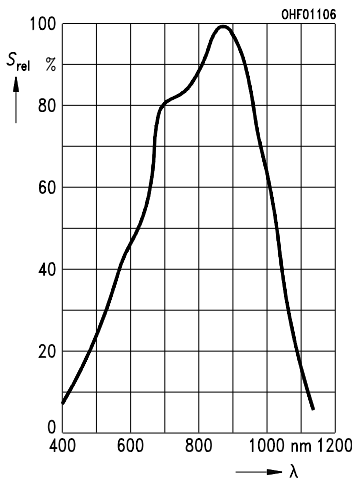
| Bezeichnung<br>Description   | Symbol<br>Symbol          | Wert<br>Value |             |             |            | Einheit<br>Unit |
|--|---------------------------|---------------|-------------|-------------|------------|-----------------|
|  |                           | -2            | -3          | -4          | -5         |                 |
| Fotostrom, $\lambda = 950 \text{ nm}$<br>Photocurrent<br>$E_e = 0.5 \text{ mW/cm}^2$ , $V_{CE} = 5 \text{ V}$<br>$E_v = 1000 \text{ lx}$ .<br>Normlicht/standard light A<br>$V_{CE} = 5 \text{ V}$ | $I_{PCE}$                 | 80 ... 160    | 125 ... 250 | 200 ... 400 | $\geq 320$ | $\mu\text{A}$   |
|  | $I_{PCE}$                 | 0.38          | 0.6         | 0.95        | 1.4        | mA              |
| Anstiegszeit/Abfallzeit<br>Rise and fall time<br>$I_C = 1 \text{ mA}$ , $V_{CC} = 5 \text{ V}$ , $R_L = 1 \text{ k}\Omega$   | $t_r, t_f$                | 5             | 7           | 9           | 12         | $\mu\text{s}$   |
| Kollektor-Emitter-Sättigungsspannung<br>Collector-emitter saturation voltage<br>$I_C = I_{PCEmin}^1) \times 0.3$<br>$E_e = 0.5 \text{ mW/cm}^2$  | $V_{CEsat}$               | 150           | 150         | 150         | 150        | mV              |
| Stromverstärkung<br>Current gain<br>$E_e = 0.5 \text{ mW/cm}^2$ , $V_{CE} = 5 \text{ V}$   | $\frac{I_{PCE}}{I_{PCB}}$ | 140           | 210         | 340         | 530        |                 |

1)  $I_{PCEmin}$  ist der minimale Fotostrom der jeweiligen Gruppe

1)  $I_{PCEmin}$  is the min. photocurrent of the specified group

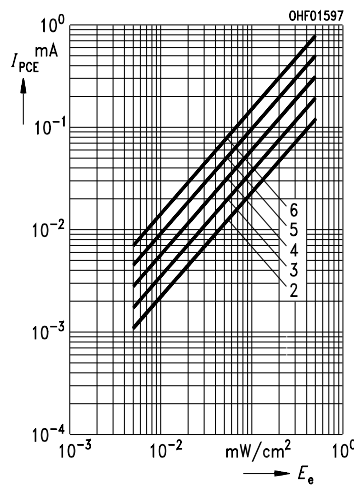
### Relative spectral sensitivity

$$S_{rel} = f(\lambda)$$



### Photocurrent

$$I_{PCE} = f(E_e), V_{CE} = 5 \text{ V}$$



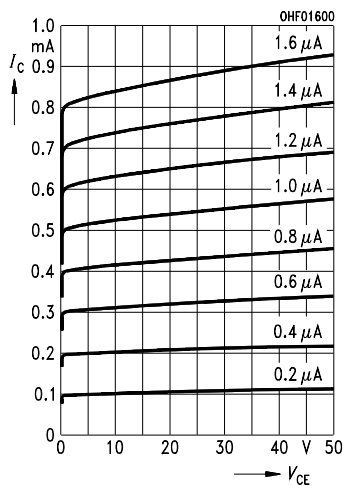
### Total power dissipation

$$P_{tot} = f(T_A)$$



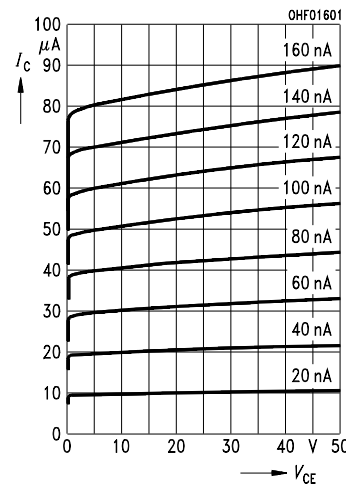
### Output characteristics

$$I_C = f(V_{CE}), I_B = \text{Parameter}$$



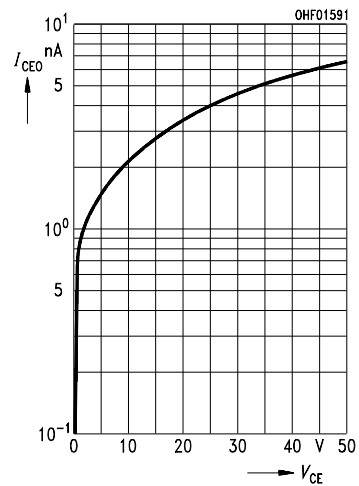
### Output characteristics

$$I_C = f(V_{CE}), I_B = \text{Parameter}$$



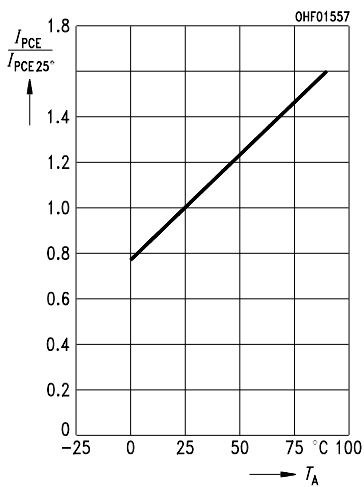
### Dark current

$$I_{CEO} = f(V_{CE}), E = 0$$



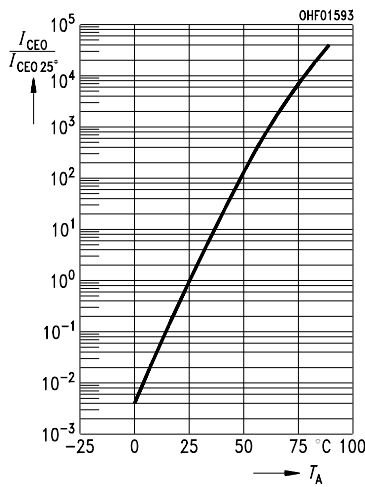
### Photocurrent

$$I_{PCE}/I_{PCE25^\circ} = f(T_A), V_{CE} = 5 \text{ V}$$



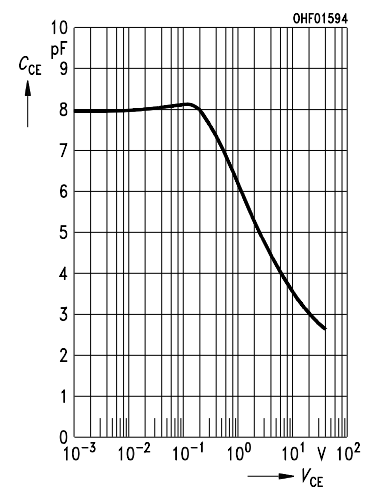
### Dark current

$$I_{CEO}/I_{CEO25^\circ} = f(T_A), V_{CE} = 25 \text{ V}, E = 0$$



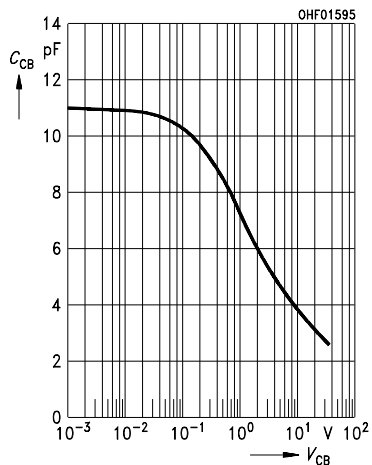
### Collector-emitter capacitance

$$C_{CE} = f(V_{CE}), f = 1 \text{ MHz}, E = 0$$



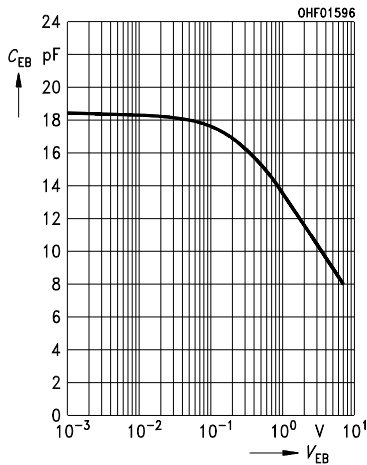
### Collector-emitter capacitance

$$C_{CB} = f(V_{CB}), f = 1 \text{ MHz}, E = 0$$



### Emitter-base capacitance

$$C_{EB} = f(V_{EB}), f = 1 \text{ MHz}, E = 0$$



### Directional characteristics $S_{rel} = f(\varphi)$

